

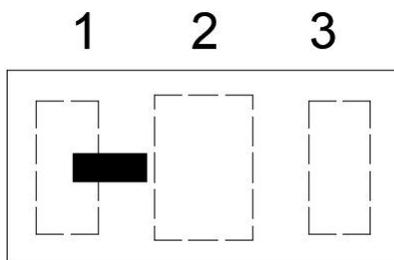
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

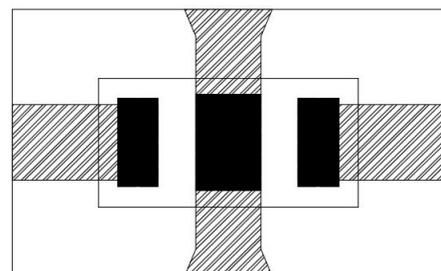
NO.	Parameter	Frequency	SPC		
			MIN	Typ	Max.
1	Insertion Loss (dB)	1880 ~ 2025 MHz	/	0.8	1.2
2	Attenuation (dB)	2400~2500 MHz	25	31	/
		4020~4045 MHz	25	30	/
		6030~6075 MHz	25	30	/
3	VSWR	1880 ~ 2025 MHz	/	1.2	1.6
4	In/Output Impedance ( $\Omega$ )	50			
<b>Operating &amp; Storage Condition (Component)</b> Operation Temperature Range: -40°C ~ +85°C Storage Temperature Range: -40°C ~ +85°C					
<b>Storage Condition before Soldering (Included packaging material)</b> Storage Temperature Range: +5 ~ +40 °C Humidity: 30 to 70% relative humidity					

### Construction

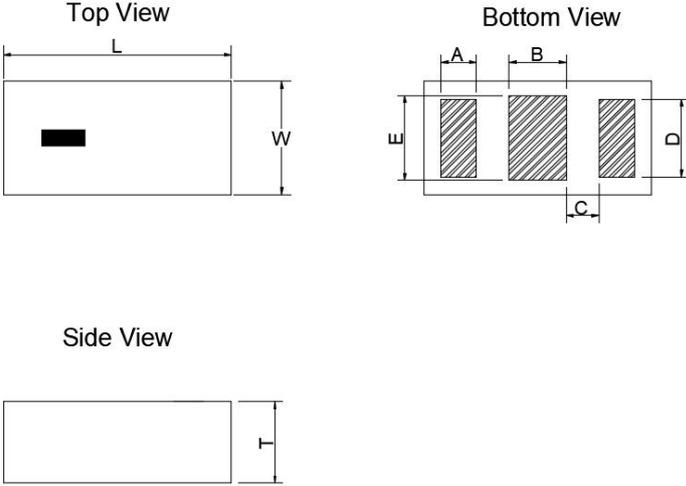


PIN	Connection
1	Input Port
2	GND
3	Output Port

### Mounting Considerations



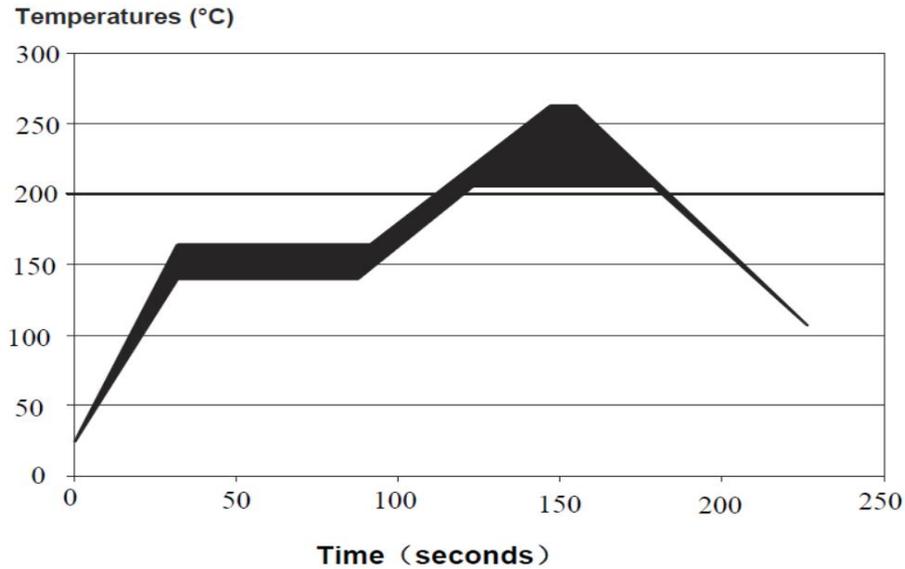
### Dimensions

Figure	Symbol	Dimension (mm)
	L	1.6±0.15
	W	0.8±0.15
	T	0.7 MAX
	A	0.25±0.10
	B	0.40±0.10
	C	0.23±0.05
	D	0.55±0.10
E	0.60±0.10	

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.